

# DATA SHEET

**74F174**

Hex D flip-flops

Product specification

1988 Oct 07

IC15 Data Handbook



# Hex D flip-flop

# 74F174

## FEATURES

- Six edge-triggered D-type flip-flops
- Buffered common Clock
- Buffered, asynchronous Master Reset

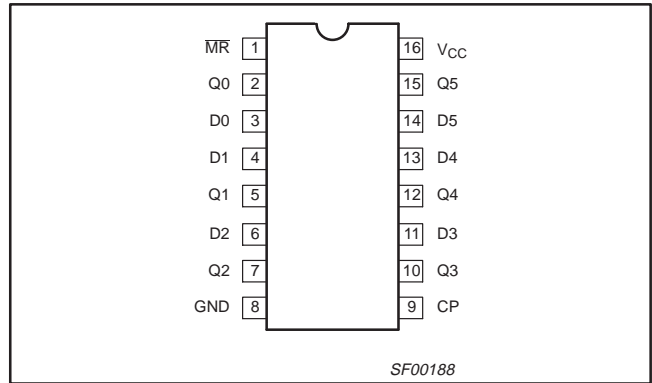
## DESCRIPTION

The 74F174 has six edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ( $\overline{MR}$ ) inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the Low-to-High clock transition is transferred to the corresponding flip-flop's Q output.

All Q outputs will be forced Low independent of Clock or Data inputs by a Low voltage level on the  $\overline{MR}$  input. The device is useful for applications where true outputs only are required, and the Clock and Master Reset are common to all storage elements.

## PIN CONFIGURATION



## ORDERING INFORMATION

TYPE	TYPICAL $f_{MAX}$	TYPICAL SUPPLY CURRENT (TOTAL)
74F174	100MHz	35mA

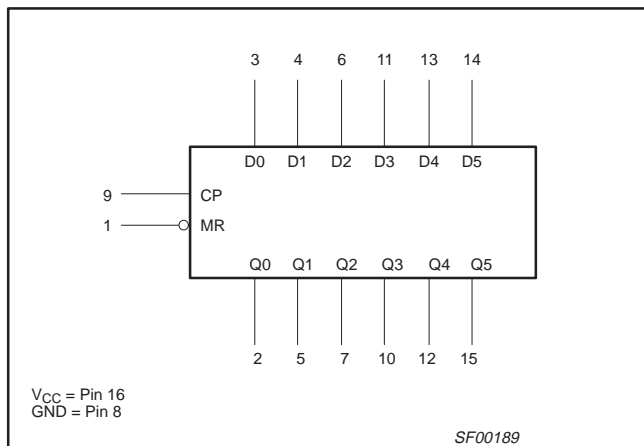
DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$ , $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$	PKG DWG #
16-pin plastic DIP	N74F174N	SOT38-4
16-pin plastic SO	N74F174D	SOT109-1

## INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

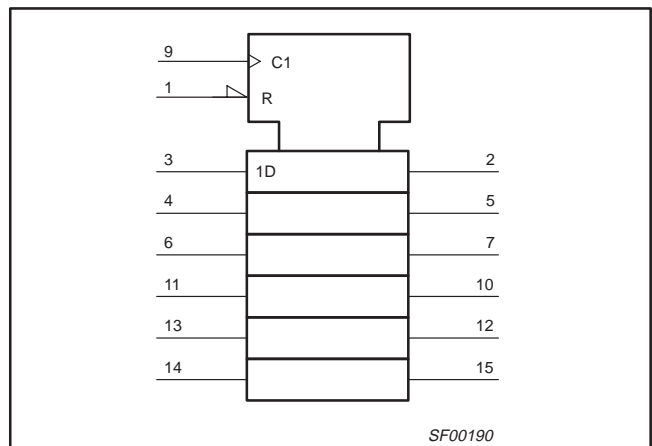
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0–D5	Data inputs	1.0/1.0	20 $\mu$ A/0.6mA
CP	Clock Pulse input (active rising edge)	1.0/1.0	20 $\mu$ A/0.6mA
$\overline{MR}$	Master Reset input (active-Low)	1.0/1.0	20 $\mu$ A/0.6mA
Q0–Q5	Outputs	50/33	1.0mA/20mA

**NOTE:** One (1.0) FAST unit load is defined as: 20 $\mu$ A in the High state and 0.6mA in the Low state.

## LOGIC SYMBOL



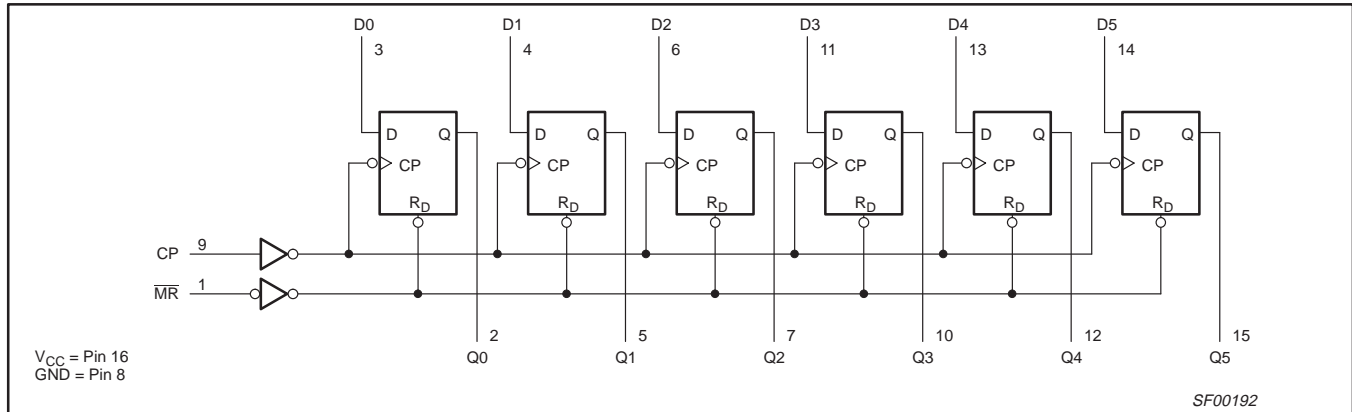
## IEC/IEEE SYMBOL



# Hex D flip-flop

74F174

## LOGIC DIAGRAM



## FUNCTION TABLE

INPUTS			OUTPUTS	OPERATING MODE
MR	CP	D	Qn	
L	X	X	L	Reset (clear)
H	↑	h	H	Load "1"
H	↑	l	L	Load "0"

H = High voltage level

L = Low voltage level

X = Don't care

↑ = Low-to-High Clock transition

h = High voltage level one set-up time prior to the Low-to-High Clock transition.

l = Low voltage level one set-up time prior to the Low-to-High Clock transition.

## ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device.)

Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	40	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

## Hex D flip-flop

74F174

## DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS <sup>1</sup>		LIMITS			UNIT
				MIN	TYP <sup>2</sup>	MAX	
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX	±10%V <sub>CC</sub>	2.5			V
		V <sub>IH</sub> = MIN, I <sub>OH</sub> = MAX	±5%V <sub>CC</sub>	2.7	3.4		
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX	±10%V <sub>CC</sub>		0.30	0.50	V
		V <sub>IH</sub> = MIN, I <sub>OL</sub> = MAX	±5%V <sub>CC</sub>		0.30	0.50	
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = I <sub>IK</sub>			-0.73	-1.2	V
I <sub>I</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7.0V				100	μA
I <sub>IH</sub>	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7V				20	μA
I <sub>IL</sub>	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5V				-0.6	mA
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>	V <sub>CC</sub> = MAX		-60		-150	mA
I <sub>CC</sub>	Supply current (total)	V <sub>CC</sub> = MAX, D <sub>n</sub> = $\overline{MR}$ = 4.5V, CP = ↑			35	45	mA

## NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
- Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

## AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			V <sub>CC</sub> = +5.0V T <sub>amb</sub> = +25°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			V <sub>CC</sub> = +5.0V ± 10% T <sub>amb</sub> = 0°C to +70°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
f <sub>MAX</sub>	Maximum clock frequency	Waveform 1	80	100		80		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to Q <sub>n</sub>	Waveform 1	3.5 4.5	5.5 6.0	8.0 10.0	3.5 4.5	9.0 11.0	ns
t <sub>PHL</sub>	Propagation delay $\overline{MR}$ to Q <sub>n</sub>	Waveform 2	5.0	8.5	14.0	5.0	15.0	ns

## AC SETUP REQUIREMENTS

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			V <sub>CC</sub> = +5.0V T <sub>amb</sub> = +25°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			V <sub>CC</sub> = +5.0V ± 10% T <sub>amb</sub> = 0°C to +70°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
t <sub>S</sub> (H) t <sub>S</sub> (L)	Setup time, High or Low D <sub>n</sub> to CP	Waveform 3	4.0 4.0			4.0 4.0		ns
t <sub>H</sub> (H) t <sub>H</sub> (L)	Hold time, High or Low D <sub>n</sub> to CP	Waveform 3	0.0 0.0			0.0 0.0		ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	CP Pulse width, High or Low	Waveform 1	4.0 6.0			4.0 6.0		ns
t <sub>w</sub> (L)	$\overline{MR}$ Pulse width, Low	Waveform 2	5.0			5.0		ns
t <sub>REC</sub>	Recovery time, $\overline{MR}$ to CP	Waveform 2	5.0			5.0		ns

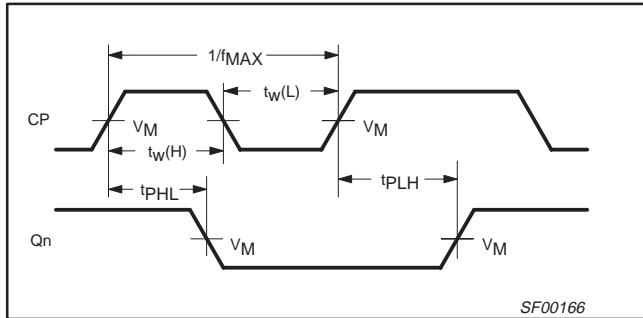
# Hex D flip-flop

74F174

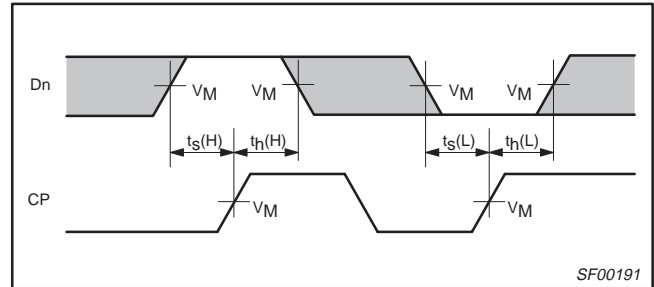
## AC WAVEFORMS

For all waveforms,  $V_M = 1.5V$ .

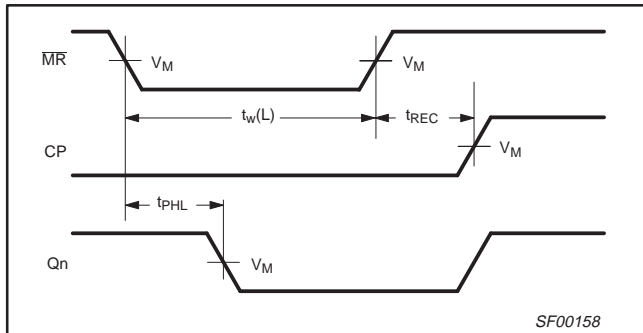
The shaded areas indicate when the input is permitted to change for predictable output performance.



**Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency**

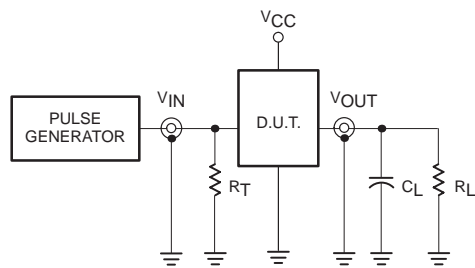


**Waveform 3. Data Setup and Hold Times**

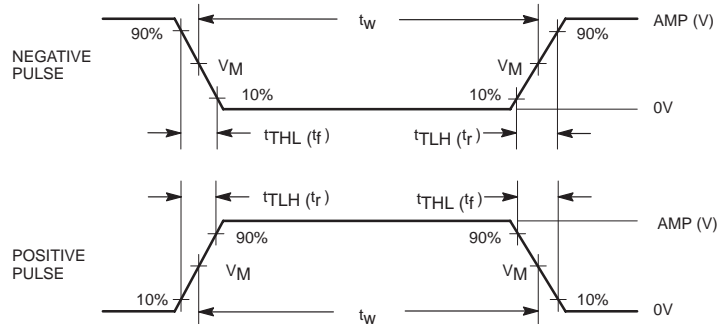


**Waveform 2. Master Reset Pulse Width, Master Reset to Output Delay and Master Reset to Clock recovery Time**

## TEST CIRCUIT AND WAVEFORMS



**Test Circuit for Totem-Pole Outputs**



**Input Pulse Definition**

**DEFINITIONS:**

- $R_L$  = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.
- $C_L$  = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.

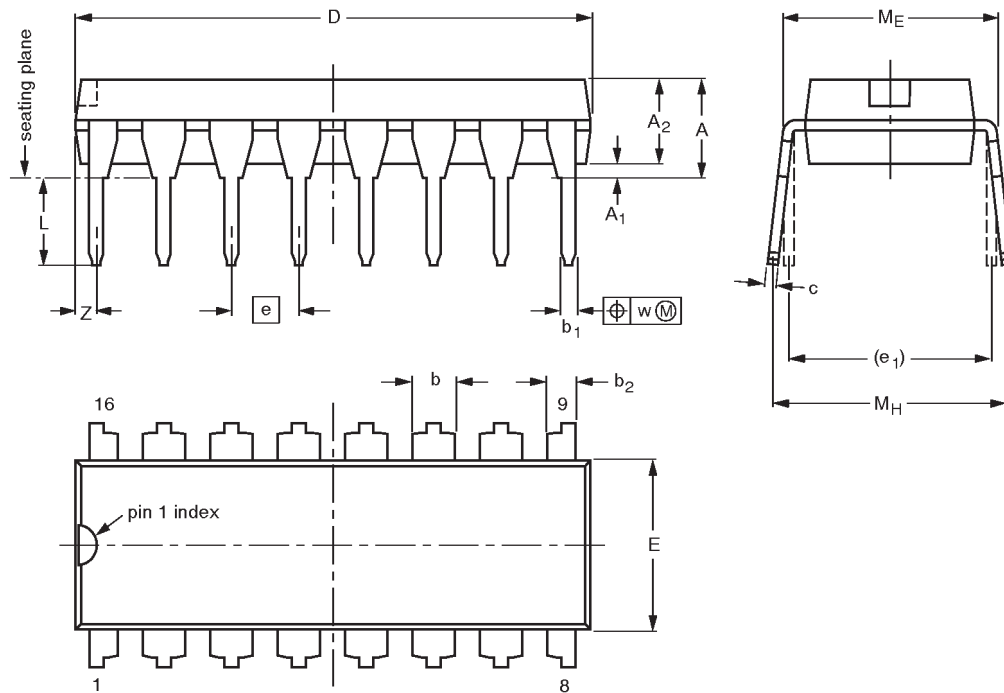
family	INPUT PULSE REQUIREMENTS					
	amplitude	$V_M$	rep. rate	$t_w$	$t_{TLH} (t_r)$	$t_{THL}$
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

# Hex D flip-flops

74F174

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



**DIMENSIONS** (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

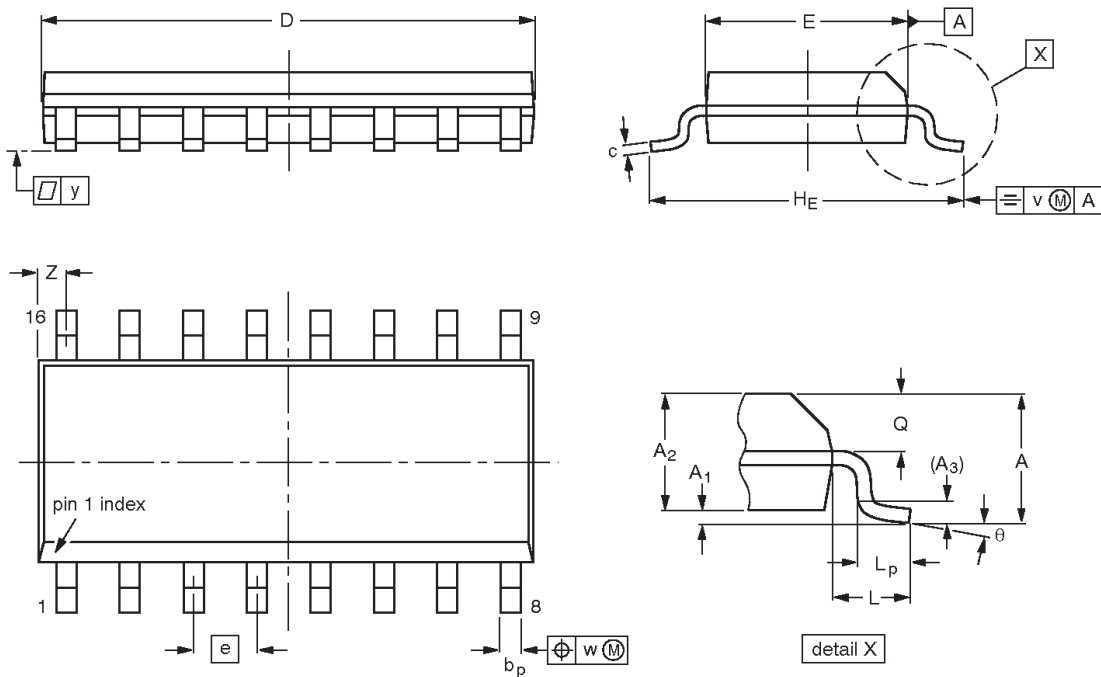
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-4						92-11-17 95-01-14

# Hex D flip-flops

74F174

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

**Note**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07S	MS-012AC				95-01-23 97-05-22

## Hex D flip-flops

74F174

## Data sheet status

Data sheet status	Product status	Definition <sup>[1]</sup>
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

## Definitions

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Application information** — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

## Disclaimers

**Life support** — These products are not designed for use in life support appliances, devices or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

**Right to make changes** — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Philips Semiconductors  
811 East Arques Avenue  
P.O. Box 3409  
Sunnyvale, California 94088-3409  
Telephone 800-234-7381

© Copyright Philips Electronics North America Corporation 1998  
All rights reserved. Printed in U.S.A.

print code

Date of release: 10-98

Document order number:

9397-750-05089

*Let's make things better.*